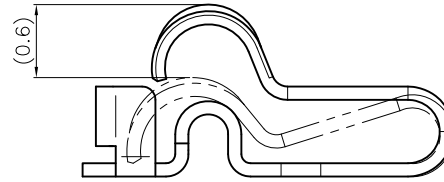
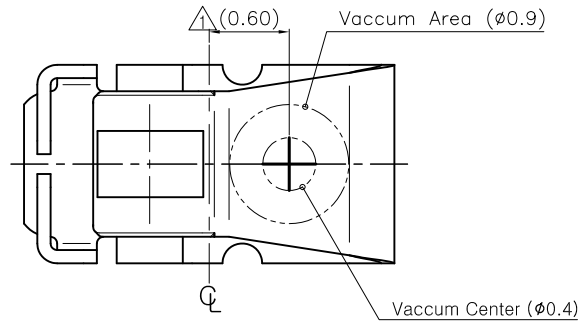
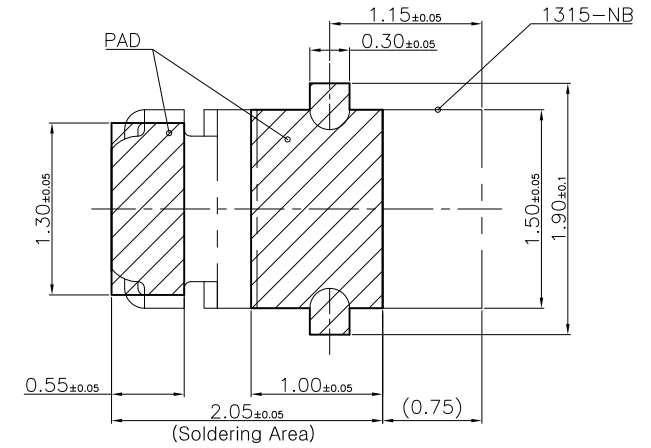


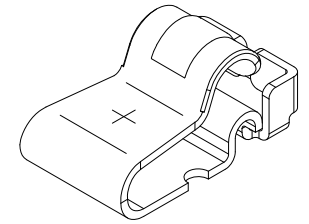
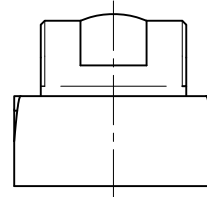
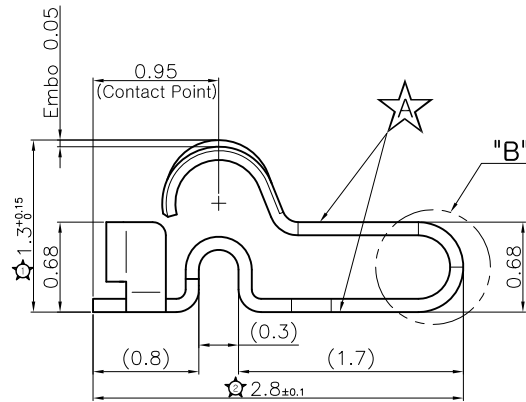
Rev No.	Description of Revision	Date	Name	Reviewed	Approved	ECN No.
△ X 1	각인추가 (고객요청)	2013.10.21	J.H.Cho	Y.J.Park	S.K.Hong	



SIMULATION

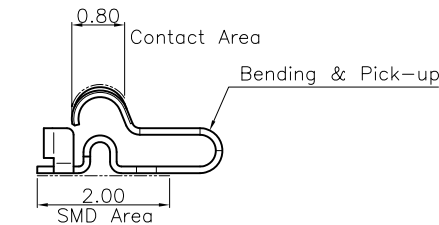


RECOMMENDED PCB LAYOUT(Top View)



***NOTE**

1. PLATING
 - Contact Area : Au 0.1 μ m Min over Ni 1.5~4.0 μ m.
 - SMD Area : Au 0.05 μ m Min over Ni 1.50~4.0 μ m.
 - Bending & Pick-up : Ni 1.5~3.5 μ m.
2. ☆: C.T.Q
3. ☆: 평탄도 0.05 Max.
4. Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~80% 범위 내
(0.36~0.48mm) => (0.82~0.94mm)
* CONTACT 가동거리(Max)는 0.6mm 이상으로 한다.
5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.
6. 일반 공차 ±0.1 적용 할 것.



PLATING AREA (SC=2/1)

1	Contact	Ti-Cu	Note.1	t0.1
No	Descriptions	Material	Finish	Remarks
General Tolerance		Scale N/S Units mm	Sheet	TITLE HJ-1315-NB ANTENNA CONTACT Customer Drawing
Dimension	mm (°)	Date 2013. 06. 26	1 of 1	
X	± 0.2	Drawn J.H. Cho 2013/06/28	Checked Y.J. Park 2013/06/28	
X.X	± 0.1	Reviewed S.K. Hong 2013/06/28	Approved	
X.XX	± 0.05	HYUPJIN CONNECTOR		SW No.
X.XXX	± 0.01			DWG No.
ANGLE	± 1°			Rev. 1

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